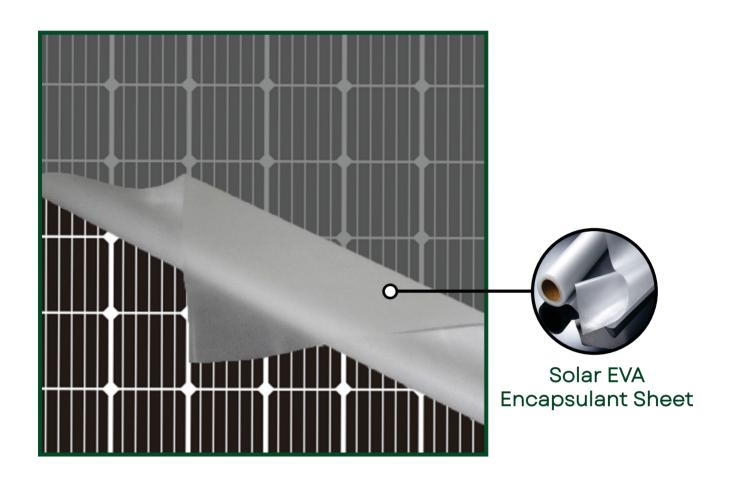
# PIX - ULTRA FAST CURE EVA ENCAPSULANT FILM: TOP LAYER - PIX UFC-T





## **ABOUT US**

PIXON houses clean room and environment controlled facility up to 1 GW manufacturing line for EVA Encapsulant films. PIXON Ultra Fast Cure EVA Encapsulant Films are specifically designed for enhancing the durability and increasing the performance of solar modules and are suitable for all types of Crystalline and Thin film PV modules with shorter cycling time that speeds up your module production with Excellent Transparency, High Reflectivity (Back side Film) increased Production Yield, Snail Trail Resistant, PID-Resistant, Lower Shrinkage, Excellent Performance with UV and Weather Stability.

PIXON EVA Encapsulant Film is proven for single stage as well as short cycle Multi Stage Lamination Processes.

### **CERTIFICATIONS**



TUV tested - DH, EVA Encapsulant Thermal & Electrical Properties TUV CTI Report : IEC 60112:2020

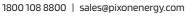


UL Certified Certificate Number E526148

 $^{\star}$ Due to continuous product updation, specifications may change without notice.

#### PIXON GREEN ENERGY PRIVATE LIMITED

Manufacturing Unit: R.S. No.: 157/1, 158/1, 158/2, 165/1, 166 of Khijadiya Nana, R.S. No.: 15/1, Rajkot – Jamnagar Highway, Paddhari, Rajkot – 360110





# TECHNICAL DATASHEET



## PIX ULTRA FAST CURE TOP EVA ENCAPSULANT FILM

#### Technical Parameters For PIX UFC-T

	Particulars	Test Method	Unit	Values
	Thickness	ASTM D 6988	μm	0.45 - 0.65 (± 5)
	Width	Scale	mm	Up to 1335 (As per Customer Requirement)
Physical	Melting Point	ISO 11357	°C	70 ± 3
Phy	GSM	ASTM D 6776	g/m²	≥390 (±20)
	Density	ASTM D 792	g/cm³	0.92 - 0.96
	VA Content	26 - 33	%	28
mal	Melt Index	ASTM D 1238	g/10min	25± 3
Thermal	Thermal Shrinkage	1600C/5 min On Glass Plate	%	≤2% MD,≤1.5 TD
	Water Absorption Test	ISO 62:200805	%	< 0.1
ical	Dielectric Strength	ASTM D 149 - 20	kv/mm	>25
Electrical	Volume Resistivity	ASTM D 257	Ohm.cm	$\geq 1 \times 10^{16}$
	UV Cut Off	ASTM E 424	_	UV- Transparent
Optical	Transmittance	ASTM D 424	%	≥91
	Refractive Index	ISO 489	_	1.48
nical	Peel Strength (EVA Encapsulant to Glass)	ASTM D 903	N/cm	≥75
	Tensile Strength	ASTM D 638	MPa	15 ± 3
Mechanical	Elongation	ASTM D 638	%	≥500
_	Shore hardness	ASTM D 2240	SHORE-A	70 ± 5
Chemical	Gel Content	ASTM D 2765 / Oven Method	%	≥ 75

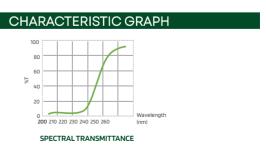
Lamination Properties	Lamination Parameter	Single Stage	Double Stage(Stage 1)	Double Stage(Stage 2)
	Vaccum Time	3 - 5 min	3 - 4 min	-
	Lamination Time	7 min	2 - 4 min	5 - 7 min
	Temparature	148 - 152°C	148 - 152°C	-

\*Laminator recipe depends on type of laminator.

- Temperature and Vacuum to be uniformly maintained across the laminator.
- $Vacuum\ to\ be\ applied\ at\ -760\ mm\ Hg,\ Periodic\ calibration\ of\ the\ machine\ input\ parameters\ to\ be\ done\ by\ Machine\ User.$
- hence Extensive trials are suggested to get the desired results.

PACKAGING INFORMATION					
Unless specified, below is the standard packing data (for 500 micron thickness, 1123 mm width)					
Length/Roll	150 Meters	300 meters			
Nos of Rolls/Pallet	12	4			
Total Linear Meters / Pallet	1800	1200			
Total SQM / Pallet	2021.4	1347.6			

Each Roll is sealed in a protective bag in corrugated box | Boxes are strapped on suitable pallets with Protection Angle Board.



Storage Condition and Shelf Life: Store in undamaged original packaging, temperature between 20°C and 30°C and humidity between 50-60% RH. Recommended use within 9 months from date of manufacture.

- The above technical information represents the typical range of properties and is believed to be correct as on date.
  This data should however not be used to establish specification limits or used as basis for design.
  PIXON gives no warranty and assumes no liability in connection with any use of this information and is subject to the PIXON general terms and conditions.
- Lamination parameters and Quality of other components of the laminate during module manufacturing impact on the overall performance of the module, and hence we recommend the user to carry out intensive trials to test suitability of this product and module laminating conditions.